# **General Purpose Transistors**

# **NPN Silicon**

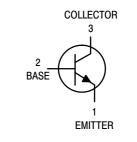
#### Features

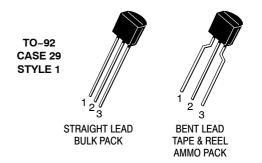
• Pb-Free Packages are Available\*



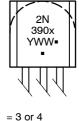
# **ON Semiconductor®**

http://onsemi.com





#### MARKING DIAGRAMS



x = 3 or 4 Y = Year WW = Work Week = = Pb-Free Package

(Note: Microdot may be in either location)

#### **ORDERING INFORMATION**

See detailed ordering and shipping information in the package dimensions section on page 3 of this data sheet.

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Collector – Emitter Voltage	V <sub>CEO</sub>	40	Vdc
Collector-Base Voltage	V <sub>CBO</sub>	60	Vdc
Emitter – Base Voltage	V <sub>EBO</sub>	6.0	Vdc
Collector Current – Continuous	Ι <sub>C</sub>	200	mAdc
Total Device Dissipation @ T <sub>A</sub> = 25°C Derate above 25°C	P <sub>D</sub>	625 5.0	mW mW/°C
Total Device Dissipation @ T <sub>C</sub> = 25°C Derate above 25°C	P <sub>D</sub>	1.5 12	W mW/°C
Operating and Storage Junction Temperature Range	T <sub>J</sub> , T <sub>stg</sub>	-55 to +150	°C

#### THERMAL CHARACTERISTICS (Note 1)

Characteristic	Symbol	Max	Unit
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	200	°C/W
Thermal Resistance, Junction-to-Case	$R_{\theta JC}$	83.3	°C/W

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

1. Indicates Data in addition to JEDEC Requirements.

\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

## **ELECTRICAL CHARACTERISTICS** (T<sub>A</sub> = $25^{\circ}$ C unless otherwise noted)

C C	Symbol	Min	Max	Unit		
OFF CHARACTERISTICS						
Collector – Emitter Breakdown Voltag	ge (Note 2) ( $I_C$ = 1.0 mAdc, $I_B$ = 0)		V <sub>(BR)CEO</sub>	40	-	Vdc
Collector - Base Breakdown Voltage	(I <sub>C</sub> = 10 μAdc, I <sub>E</sub> = 0)		V <sub>(BR)CBO</sub>	60	-	Vdc
Emitter – Base Breakdown Voltage (I	<sub>E</sub> = 10 μAdc, I <sub>C</sub> = 0)		V <sub>(BR)EBO</sub>	6.0	-	Vdc
Base Cutoff Current (V <sub>CE</sub> = 30 Vdc,	V <sub>EB</sub> = 3.0 Vdc)		I <sub>BL</sub>	-	50	nAdc
Collector Cutoff Current (V <sub>CE</sub> = 30 V	dc, V <sub>EB</sub> = 3.0 Vdc)		I <sub>CEX</sub>	-	50	nAdd
ON CHARACTERISTICS						
DC Current Gain (Note 2) $(I_C = 0.1 \text{ mAdc}, V_{CE} = 1.0 \text{ Vdc})$		2N3903	h <sub>FE</sub>	20	-	-
(I <sub>C</sub> = 1.0 mAdc, V <sub>CE</sub> = 1.0 Vdc)		2N3904 2N3903 2N3904		40 35 70		
(I <sub>C</sub> = 10 mAdc, $V_{CE}$ = 1.0 Vdc)		2N3903 2N3904		50 100	150 300	
(I <sub>C</sub> = 50 mAdc, V <sub>CE</sub> = 1.0 Vdc)		2N3904 2N3903 2N3904		30 60		
$(I_{C} = 100 \text{ mAdc}, V_{CE} = 1.0 \text{ Vdc})$		2N3903 2N3904		15 30		
$\begin{array}{l} \mbox{Collector}-\mbox{Emitter Saturation Voltage} \\ (I_C = 10 \mbox{ mAdc}, \ I_B = 1.0 \mbox{ mAdc}) \\ (I_C = 50 \mbox{ mAdc}, \ I_B = 5.0 \mbox{ mAdc} \end{array}$	e (Note 2)		V <sub>CE(sat)</sub>		0.2 0.3	Vdc
$\begin{array}{l} \text{Base}-\text{Emitter Saturation Voltage (N}\\ (I_{C}=10\text{ mAdc},\ I_{B}=1.0\text{ mAdc})\\ (I_{C}=50\text{ mAdc},\ I_{B}=5.0\text{ mAdc}) \end{array}$	V <sub>BE(sat)</sub>	0.65 -	0.85 0.95	Vdc		
SMALL-SIGNAL CHARACTERIST	ICS				1	
Current-Gain – Bandwidth Product ( $I_C = 10 \text{ mAdc}, V_{CE} = 20 \text{ Vdc}, f = 10$	0 MHz)	2N3903 2N3904	f <sub>T</sub>	250 300		MHz
Output Capacitance (V <sub>CB</sub> = 5.0 Vdc,	I <sub>E</sub> = 0, f = 1.0 MHz)		C <sub>obo</sub>	-	4.0	pF
Input Capacitance (V <sub>EB</sub> = 0.5 Vdc, I <sub>c</sub>	<sub>2</sub> = 0, f = 1.0 MHz)		C <sub>ibo</sub>	-	8.0	pF
Input Impedance (I <sub>C</sub> = 1.0 mAdc, V <sub>CE</sub> = 10 Vdc, f = 1.	2N3903 2N3904	h <sub>ie</sub>	1.0 1.0	8.0 10	kΩ	
Voltage Feedback Ratio (I <sub>C</sub> = 1.0 mAdc, V <sub>CE</sub> = 10 Vdc, f = 1.	2N3903 2N3904	h <sub>re</sub>	0.1 0.5	5.0 8.0	X 10⁻	
Small–Signal Current Gain ( $I_C = 1.0$ mAdc, $V_{CE} = 10$ Vdc, f = 1.	2N3903 2N3904	h <sub>fe</sub>	50 100	200 400	-	
Output Admittance (I <sub>C</sub> = 1.0 mAdc, \		h <sub>oe</sub>	1.0	40	μmho	
Noise Figure (I <sub>C</sub> = 100 $\mu$ Adc, V <sub>CE</sub> = 5.0 Vdc, R <sub>S</sub> =	2N3903 2N3904	NF		6.0 5.0	dB	
SWITCHING CHARACTERISTICS						
Delay Time (Vcc = 3.0 Vc	dc, V <sub>BE</sub> = 0.5 Vdc,		t <sub>d</sub>	-	35	ns
Bise Time I <sub>C</sub> = 10 mAdo		+	1	35	ns	

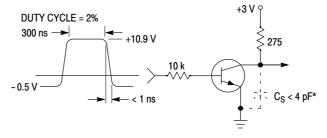
Delay Time	(V <sub>CC</sub> = 3.0 Vdc, V <sub>BE</sub> = 0.5 Vdc,	t <sub>d</sub>	-	35	ns
Rise Time	$I_{\rm C} = 10 \text{ mAdc}, I_{\rm B1} = 1.0 \text{ mAdc})$	t <sub>r</sub>	-	35	ns
Storage Time		t <sub>s</sub>	-	175 200	ns
Fall Time		t <sub>f</sub>	-	50	ns

2. Pulse Test: Pulse Width  $\leq$  300 µs; Duty Cycle  $\leq$  2%.

#### **ORDERING INFORMATION**

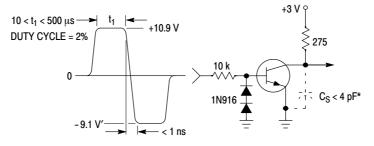
Device	Package	Shipping <sup>†</sup>
2N3903RLRM	TO-92	2000 / Ammo Pack
2N3904	TO-92	5000 Units / Bulk
2N3904G	TO-92 (Pb-Free)	5000 Units / Bulk
2N3904RLRA	TO-92	2000 / Tape & Reel
2N3904RLRAG	TO-92 (Pb-Free)	2000 / Tape & Reel
2N3904RLRM	TO-92	2000 / Ammo Pack
2N3904RLRMG	TO-92 (Pb-Free)	2000 / Ammo Pack
2N3904RLRP	TO-92	2000 / Ammo Pack
2N3904RLRPG	TO-92 (Pb-Free)	2000 / Ammo Pack
2N3904RL1G	TO-92 (Pb-Free)	2000 / Tape & Reel
2N3904ZL1	TO-92	2000 / Ammo Pack
2N3904ZL1G	TO-92 (Pb-Free)	2000 / Ammo Pack

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.



\* Total shunt capacitance of test jig and connectors

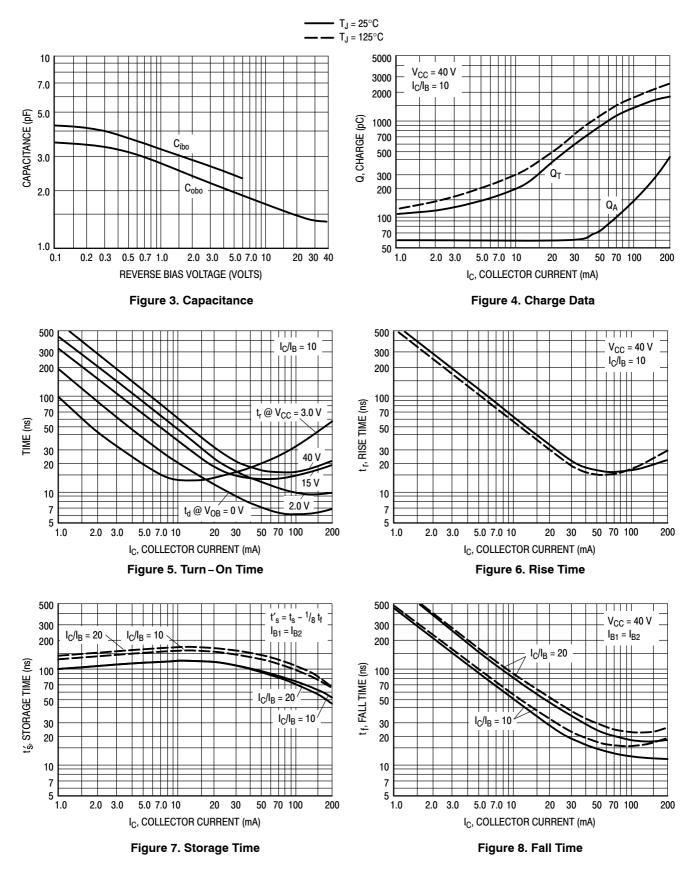
#### Figure 1. Delay and Rise Time Equivalent Test Circuit

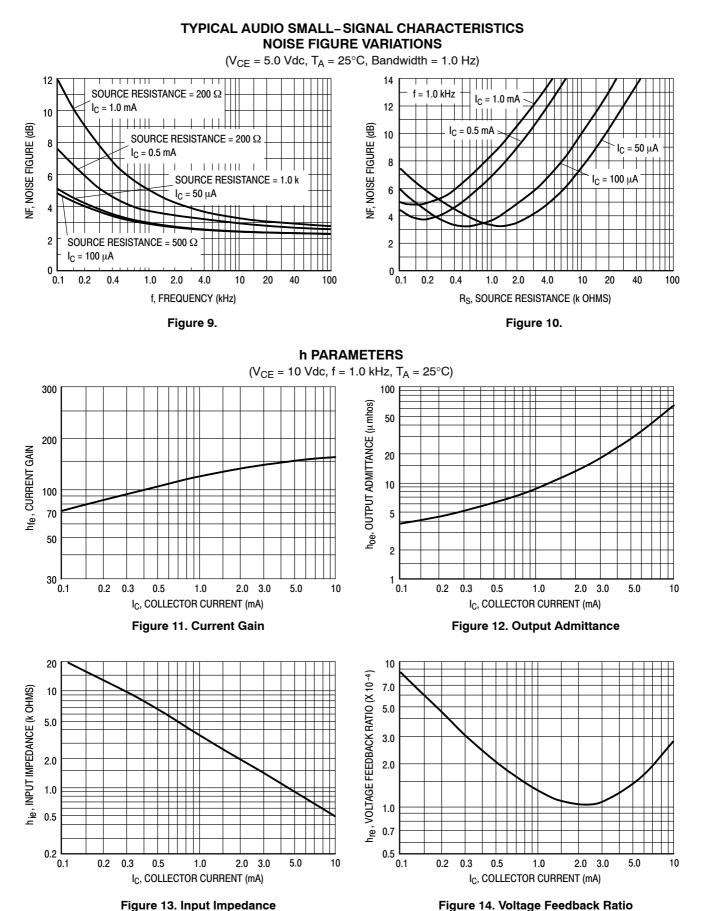


\* Total shunt capacitance of test jig and connectors

Figure 2. Storage and Fall Time Equivalent Test Circuit

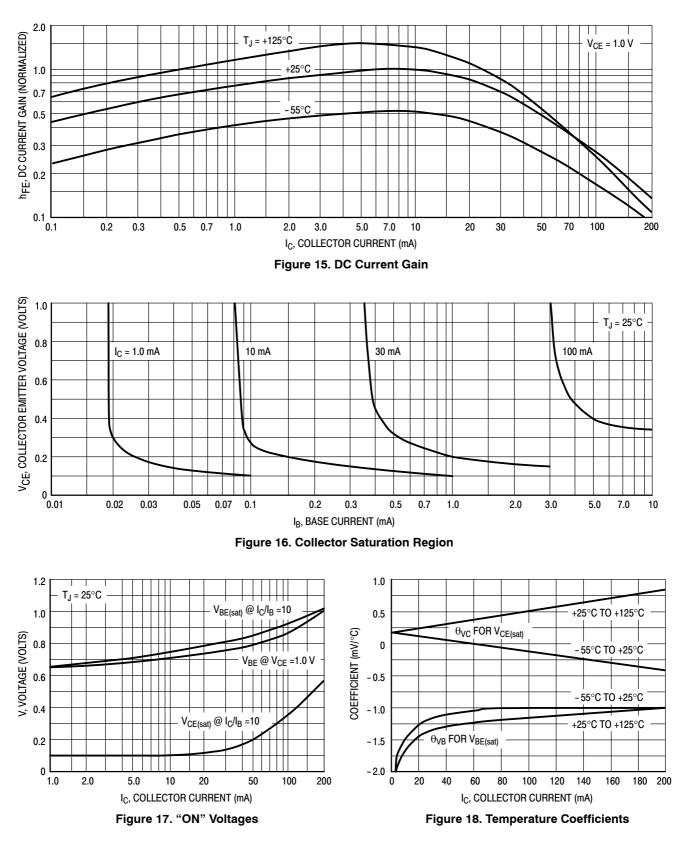
### **TYPICAL TRANSIENT CHARACTERISTICS**





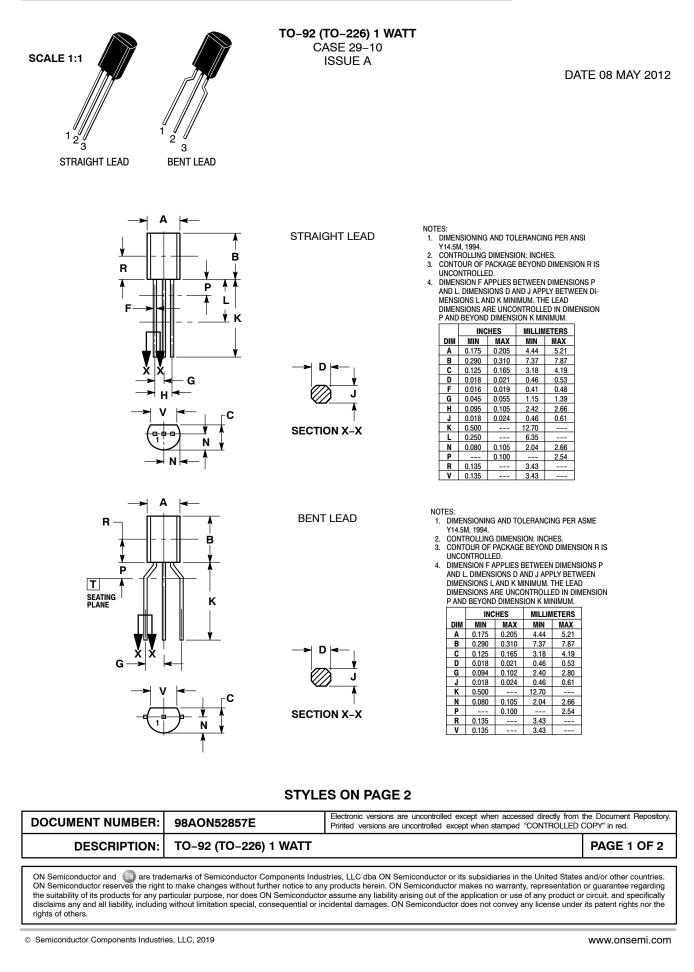
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### **TYPICAL STATIC CHARACTERISTICS**



#### MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS





#### **TO-92 (TO-226) 1 WATT** CASE 29-10 ISSUE A

### DATE 08 MAY 2012

	EMITTER BASE COLLECTOR								
	GATE SOURCE & SUBSTRATE DRAIN								
STYLE 11: PIN 1. 2. 3.	ANODE CATHODE & ANODE CATHODE	STYLE 12: PIN 1. 2. 3.	MAIN TERMINAL 1 Gate Main Terminal 2	STYLE 13: PIN 1. 2. 3.	ANODE 1 GATE CATHODE 2	STYLE 14: PIN 1. 2. 3.	EMITTER COLLECTOR BASE	STYLE 15: PIN 1. 2. 3.	ANODE 1 CATHODE ANODE 2
STYLE 16: PIN 1. 2. 3.	ANODE GATE CATHODE	STYLE 17: PIN 1. 2. 3.	COLLECTOR BASE EMITTER	STYLE 18: PIN 1. 2. 3.	ANODE CATHODE NOT CONNECTED	STYLE 19: PIN 1. 2. 3.	GATE ANODE CATHODE	STYLE 20: PIN 1. 2. 3.	NOT CONNECTED CATHODE ANODE
STYLE 21: PIN 1. 2. 3.	COLLECTOR EMITTER BASE	STYLE 22: PIN 1. 2. 3.	SOURCE GATE DRAIN	STYLE 23: PIN 1. 2. 3.	GATE SOURCE DRAIN	STYLE 24: PIN 1. 2. 3.	EMITTER Collector/Anode Cathode	STYLE 25: PIN 1. 2. 3.	MT 1 GATE MT 2
STYLE 26: PIN 1. 2. 3.	V <sub>CC</sub> GROUND 2 OUTPUT	STYLE 27: PIN 1. 2. 3.	MT SUBSTRATE MT	STYLE 28: PIN 1. 2. 3.	CATHODE ANODE GATE	STYLE 29: PIN 1. 2. 3.	NOT CONNECTED ANODE CATHODE	STYLE 30: PIN 1. 2. 3.	DRAIN GATE SOURCE
STYLE 31: PIN 1. 2. 3.	GATE DRAIN SOURCE	STYLE 32: PIN 1. 2. 3.	BASE COLLECTOR EMITTER	STYLE 33: PIN 1. 2. 3.	RETURN INPUT OUTPUT	STYLE 34: PIN 1. 2. 3.	INPUT Ground Logic	STYLE 35: PIN 1. 2. 3.	GATE COLLECTOR EMITTER

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